

PATENT APPLICATION Docket No. 8750-045 Client Ref. No. SPX200306-0020-US

COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled MULTI-CHIP MODULE HAVING BONDING WIRES AND METHOD OF FABRICATING THE SAME, the specification of which:

was filed on July 31, 2003 as Application No. 10/632,700

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, Sec. 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Sec. 119 (a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below any foreign application for patent or inventor's certificate, or of any PCT international application having a filing date before that of the application on which priority is claimed: NONE

I hereby claim the benefit under Title 35, United States Code, Sec. 119(c) of any United States provisional application listed below: NONE

I hereby claim the benefit under Title 35, United States Code, Sec. 120 or §365(c) of any PCT international application designating the United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Sec. 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application; NONE

I hereby appoint the following attorneys to prosecute the application, to file a corresponding international application, to prosecute and transact all business in the Patent and Trademark Office connected therewith:

20575

20575 PATENT TRADEMÁRK OFFICE

Attorney Name	Registration No.
Elmer W. Galbi	19,761
Jerome S. Marger	26,480
Alexander C. Johnson, Jr.	29,396
Alan T. McCollom	28,881
James G. Stewart	32,496
Stephen S. Ford	35,139
Julie L. Reed	35,349
Scott A. Schaffer	38,610
Joseph S. Makuch	39,286
James E. Harris	40,013
Kevin S. Ross	42,116
Graciela G. Cowger	42,444
Aricl Rogson	43,054
Craig R. Rogers	43,888
Hillary Brooks	45,815
Clifford D. Weston	48,307
Todd J. Iverson	53,057

Direct all telephone calls to Alan T. McCollom at (503) 222-3613 and send all correspondence to:

> MARGER JOHNSON & McCOLLOM, P.C. 1030 S.W. Morrison Street Portland, Oregon 97205

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor:

In-Ku Kang

Nov A, 1003 (Date)

Residence:

Chungcheongnam-do, Republic of Korea

Citizenship:

Republic of Korea

Post Office address: 105-1404, Wolbong Daewoo Apt., Ssangyong2-dong, Cheonan-city,

Chungcheongnam-do, Republic of Korea

Post Office address:

Full name of second joint inventor: Hee-Kook Choi Inventor's signature: Hee-Kook Choi Nov 18, 2003 (Date) Residence: Chungcheongnam-do, Republic of Korea Citizenship: Republic of Korea Post Office address: 3-1001, Moran Apt., 653, Ssangyong2-dong, Cheonan-city, Chungcheongnam-do, Republic of Korea Full name of third joint inventor: Sang-Ho An Mov 18. 2003 Inventor's signature: Sang-Ho An Residence: Kyunggi-do, Republic of Korea Citizenship: Republic of Korea Post Office address: 433-1304, Chungmycong maeul Samsung Apt., Youngtong-dong, Paldal-gu, Suwon-city, Kyunggi-do, Republic of Korea Full name of fourth joint inventor: Sang-Yeop Lee Inventor's signature: Sang - Tegp Nov 18. 2003 (Date) Residence: Chungcheongnam-do, Republic of Korea Citizenship: Republic of Korea

Chungcheongnam-do, Republic of Korea

304-1605, Hyangchon Hyundai Apt., Sinbang-dong, Cheonan-city,